# **HD74HCT237**

3-to-8-line Decoder/Demultiplexer with Address Latch

# **HITACHI**

### **Description**

The HD74HCT237 decodes a three-bit Address to one-of-eight active-high outputs. The device has a transparent latch for storage of the Address. Two Chip Selects, one active-low and one active-high, are provided to facilitate the demultiplexing, cascading, and chip-selecting functions.

The demultiplexing function is accomplished by using the Address inputs to select the desired device output, and then by using one of the Chip Select as a data input while holding the other one active.

The HD74HCT237 is the noninverting version of the HD74HCT137.

### **Features**

- LSTTL Output Logic Level Compatibility as well as CMOS Output Compatibility
- High Speed Operation:  $t_{nd}$  (A, B, C to Y) = 23 ns typ ( $C_L = 50 \text{ pF}$ )
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage:  $V_{CC} = 4.5$  to 5.5 V
- Low Input Current: 1 µA max
- Low Quiescent Supply Current:  $I_{CC}$  (static) = 4  $\mu$ A max (Ta = 25°C)



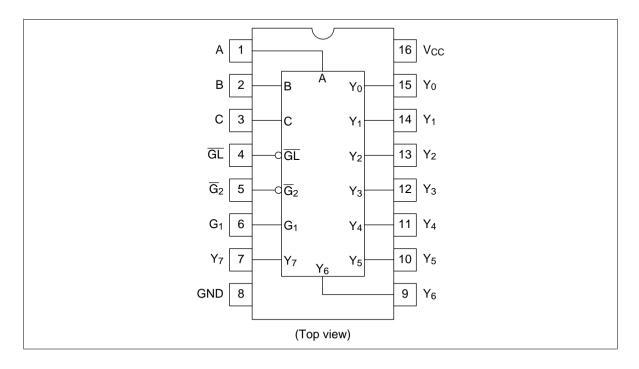
## **HD74HCT237**

## **Function Table**

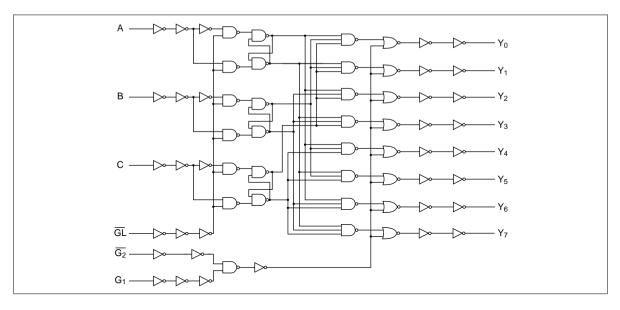
### Inputs

Enal	ble		Sele	ct		Outp	Outputs								
GL	G₁	$\overline{G}_{\scriptscriptstyle 2}$	С	В	Α	Y <sub>0</sub>	<b>Y</b> <sub>1</sub>	Y <sub>2</sub>	<b>Y</b> <sub>3</sub>	<b>Y</b> <sub>4</sub>	<b>Y</b> <sub>5</sub>	Y <sub>6</sub>	<b>Y</b> <sub>7</sub>		
Χ	Х	Н	Х	Х	Χ	L	L	L	L	L	L	L	L		
Χ	L	Χ	Х	Х	Х	L	L	L	L	L	L	L	L		
L	Н	L	L	L	L	Н	L	L	L	L	L	L	L		
L	Н	L	L	L	Н	L	Н	L	L	L	L	L	L		
L	Н	L	L	Н	L	L	L	Н	L	L	L	L	L		
L	Н	L	L	Н	Н	L	L	L	Н	L	L	L	L		
L	Н	L	Н	L	L	L	L	L	L	Н	L	L	L		
L	Н	L	Н	L	Н	L	L	L	L	L	Н	L	L		
L	Н	L	Н	Н	L	L	L	L	L	L	L	Н	L		
L	Н	L	Н	Н	Н	L	L	L	L	L	L	L	Н		
Н	Н	L	Х	Х	Х	Outp	ut Corre	spondin	g to sto	red addı	ess L; a	II others	Н		

## **Pin Arrangement**



## Logic Diagram



## **DC** Characteristics

		Ta =	: 25°C	;	Ta = ⋅ +85°0	–40 to		Test Co	onditions
Item	Symbol	Min	Тур	Max	Min	Max	Unit	V <sub>cc</sub> (V)	-
Input voltage	V <sub>IH</sub>	2.0	_	_	2.0	_	V	4.5 to 5.5	
	$V_{IL}$	_	_	8.0	_	8.0	V	4.5 to 5.5	
Output voltage	$V_{OH}$	4.4	_	_	4.4	_	V	4.5	Vin = $V_{IH}$ or $V_{IL}$ $I_{OH} = -20 \mu A$
		4.18	_	_	4.13			4.5	$I_{OH} = -4 \text{ mA}$
	V <sub>OL</sub>		_	0.1	_	0.1	V	4.5	Vin = $V_{IH}$ or $V_{IL}$ $I_{OL}$ = 20 $\mu$ A
		_	_	0.26	_	0.33		4.5	$I_{OL} = 4 \text{ mA}$
Input current	lin	_	_	±0.1	_	±1.0	μΑ	5.5	Vin = V <sub>cc</sub> or GND
Quiescent supply current	I <sub>cc</sub>	_	_	4.0	_	40	μΑ	5.5	Vin = $V_{cc}$ or GND, lout = 0 $\mu$ A

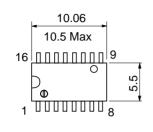
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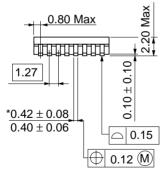
**AC Characteristics** ( $C_L = 50 \text{ pF}$ , Input  $t_r = t_f = 6 \text{ ns}$ )

		Ta =	: 25°C	;	Ta = +85°	–40 to C		Test Co	onditions
Item	Symbol	Min	Тур	Max	Min	Max	Unit	V <sub>cc</sub> (V)	-
Propagation delay	t <sub>PLH</sub>	_	21	37	_	46	ns	4.5	A, B or C to Y
time	t <sub>PHL</sub>	_	25	37	_	46		4.5	-
	t <sub>PLH</sub>	_	18	29	_	36	ns	4.5	G <sub>2</sub> to Y
	t <sub>PHL</sub>	_	14	29	_	36	_	4.5	-
	t <sub>PLH</sub>	_	16	29	_	36	ns	4.5	G₁ to Y
	t <sub>PHL</sub>	_	18	29	_	36	=	4.5	-
	t <sub>PLH</sub>	_	22	38	_	48	ns	4.5	GL to Y
	t <sub>PHL</sub>	_	27	38	_	48	=	4.5	-
Pulse width	t <sub>w</sub>	16	8	_	20	_	ns	4.5	
Setup time	t <sub>su</sub>	20	6	_	25	_	ns	4.5	
Hold time	t <sub>h</sub>	5	-1	_	5	_	ns	4.5	
Output rise/fall time	t <sub>TLH</sub> t <sub>THL</sub>	_	5	15	_	19	ns	4.5	
Input capacitance	Cin	_	5	10	_	10	pF	_	

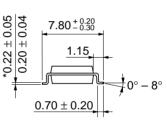
Unit: mm 19.20 20.00 Max 16 7.40 Max 6.30 1.3 1.11 Max 7.62 5.06 Max 2.54 Min 0.51 Min  $0.25^{+0.13}_{-0.05}$  $0.48 \pm 0.10$  $2.54\pm0.25$  $0^{\circ} - 15^{\circ}$ Hitachi Code DP-16 **JEDEC** Conforms EIAJ Conforms Weight (reference value) 1.07 g

Unit: mm





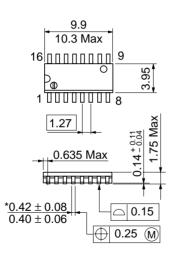


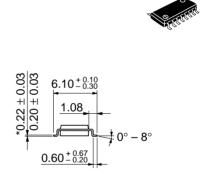


Hitachi Code	FP-16DA
JEDEC	
EIAJ	Conforms
Weight (reference value)	0.24 a

\*Dimension including the plating thickness
Base material dimension

Unit: mm





\*Dimension including the plating thickness Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.15 g

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